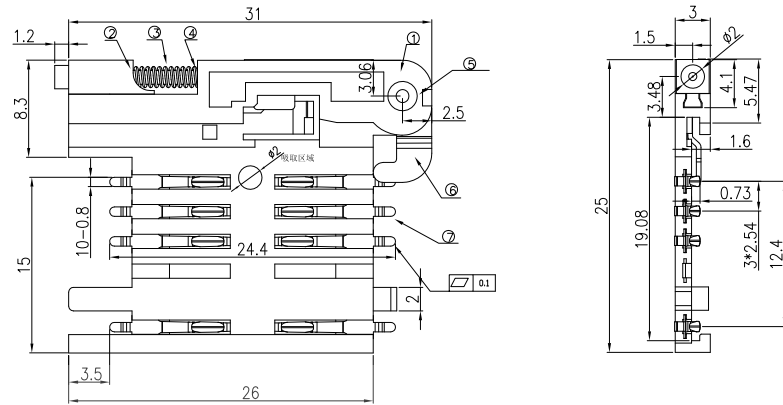


REV.	ECN NO	CONTENT	DATE	ENGINEER
A0		Initial release	/	SGF

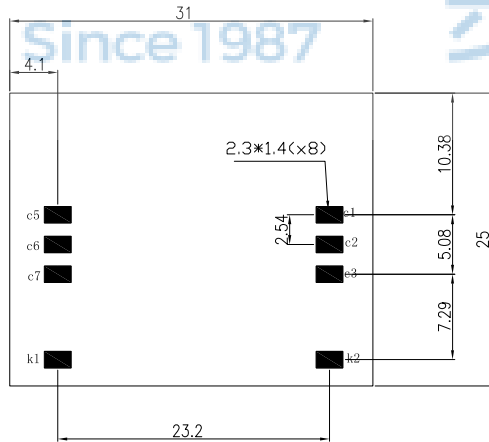


技术要求:

1. 产品外观无脏污, 刮伤, 变形现象
2. 塑体无毛边, 未射饱; 接触片无氧化, 生锈现象

备注: 接触片镀金层的厚度可根据客户的需求做变更

Current Rating :0.5A AC/DC max.
Voltage Rating :10V AC/DC
Contact Resistance:100mΩ max.
Insulation Resistance:1000MΩ min./500VDC
Normal Force: 0.5N/pin MIN.
Temperature: -40°C to 85°C .



- C1 — VCC
- C2 — RST
- C3 — CLK
- C5 — GND
- C6 — VPP
- C7 — I/O
- K1 (SW1)
- K2 (SW2)



7	端子	磷铜	8	底层镀Ni;接触区镀Au15u"
6	Z形片	不锈钢	1	
5	小轴	磷铜	1	
4	推杆	不锈钢	1	
3	弹簧	不锈钢	1	
2	按钮	LCP	1	
1	塑胶主体	LCP	1	
序号	名称	材料	数量	备注

RECOMMENDED PCB LAYOUT 未注公差±0.05

THIS DOCUMENT IS THE SOLE PROPERTY OF BBJconn Technology Co.,Ltd. Corporation AND SHOULD NOT BE USED IN WHOLE OR IN PART WITHOUT PRIOR WRITTEN PERMISSION.

PDWG,NO: 0302-1

APPD. JM_Zheng
CHKD. LYX
DR. SGF

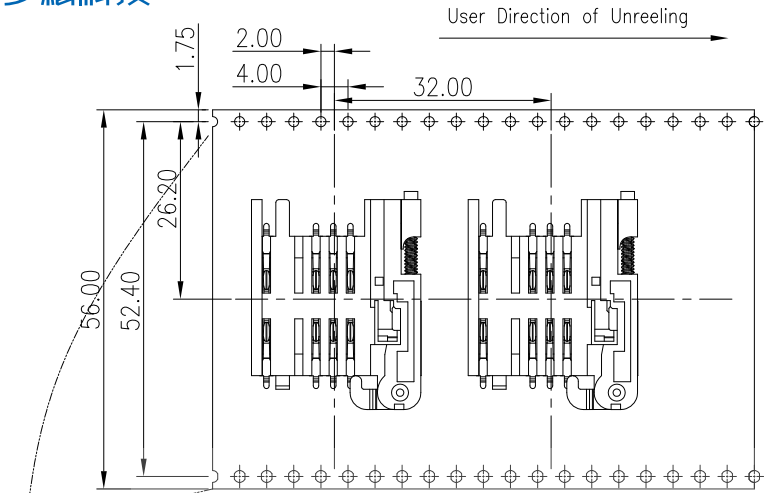
NAME: 深圳市步步精科技有限公司
卡座 8P 3.0H PIN-PUSH SIM CARD 卷装

PJ. NO.:
SIZE: A4 DRW NO.:

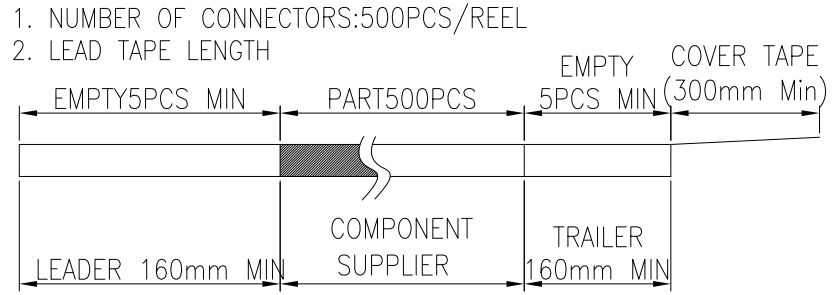
FINISH: SEE NOTES MAT'L.: SEE NOTES
SCALE: N/A REV.: A0 UNIT: mm PAGE: 1/2

REV.	ECN NO.	CONTENT	DATE	ENGINEER
A0		Initial release	/	SGF

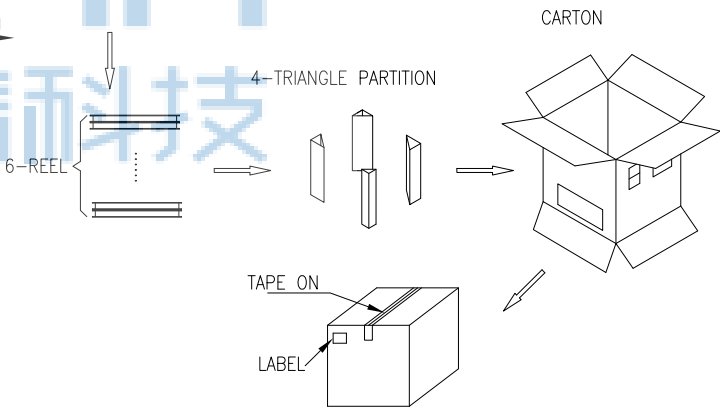
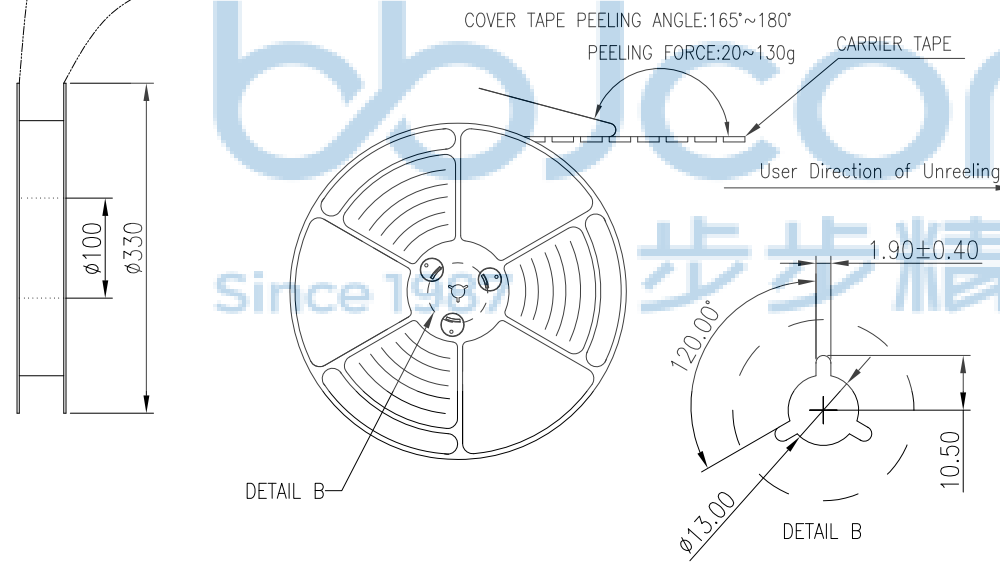
A
B
C
D
E



NOTES



3. QUANTITY: 3000PCS/CARTON



THIS DOCUMENT IS THE SOLE PROPERTY OF BBJconn Technology Co., Ltd. Corporation AND SHOULD NOT BE USED IN WHOLE OR IN PART WITHOUT PRIOR WRITTEN PERMISSION.		深圳市步步精科技有限公司	
.X: ±0.38 .XX: ±0.25 .XXX: ±0.13		X': ±3" X'': ±2" XX': ±1"	
APPD.	JM_Zheng	NAME: 卡座 8P 3.0H PIN-PUSH SIM CARD 卷装	
CHKD.	LYX	PJ. NO.:	
DR.	SGF	SIZE: A4 DRW NO.:	
PDWG.NO: 0302-1		FINISH: SEE NOTES MAT'L.: SEE NOTES	
		SCALE: N/A REV.: A0 UNIT: mm PAGE: 2/2	

1 2 3 4 5 6 7 8